

Power Schottky rectifier

Main product characteristics

$I_{F(AV)}$	2 x 3 A
V_{RRM}	40 V
T_j (max)	150° C
V_F (max)	0.57 V

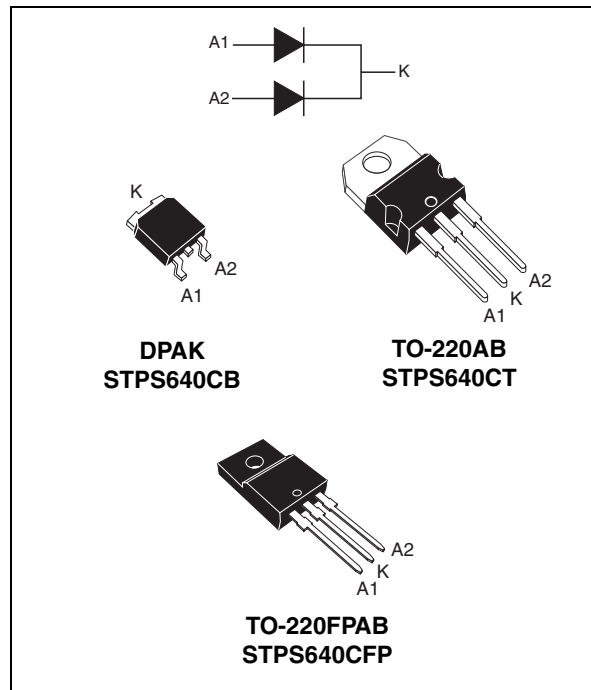
Features and benefits

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward drop voltage
- Low capacitance
- Low thermal resistance
- Insulated package: TO-220FPAB
Insulating voltage = 2000 V DC
Capacitance = 12 pF
- Avalanche capability specified

Description

Dual Schottky rectifier suited to Switch Mode Power Supplies and other Power Converters.

This device is intended for use in low and medium voltage operation, and particularly, in high frequency circuitries where low switching losses are required (free wheeling and polarity protection).



1 Characteristics

Table 1. Absolute ratings (limiting values, per diode)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		40	V
$I_{F(RMS)}$	RMS forward voltage	TO-220AB /TO-220FPAB	10	A
		DPAK	6	
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AB	3	A
		TO-220FPAB		
		DPAK		
I_{FSM}	Surge non repetitive forward current	$t_p = 10$ ms Sinusoidal	75	A
I_{RRM}	Repetitive peak reverse current	$t_p = 2$ μ s square F = 1 kHz	1	A
P_{ARM}	Repetitive peak avalanche power	$t_p = 1$ μ s $T_j = 25^\circ$ C	1300	W
T_{stg}	Storage temperature range		-65 to + 150	$^\circ$ C
T_j	Maximum operating junction temperature		150	$^\circ$ C
dV/dt	Critical rate of rise of reverse voltage		10000	V/ μ s

Table 2. Thermal resistances

Symbol	Parameter		Value	Unit	
$R_{th(j-c)}$	Junction to case	TO-220AB / DPAK	Per diode	5.5	$^\circ$ C/W
			Total	3	
		TO-220FPAB	Per diode	5.5	
			Total	5.2	
$R_{th(c)}$	Coupling	TO-220AB	0.5	$^\circ$ C/W	
		TO-220FPAB	3		

When the diodes 1 and 2 are used simultaneously :
 $\Delta T_j(\text{diode 1}) = P(\text{diode1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ$ C	$V_R = V_{RRM}$			100	μ A
		$T_j = 125^\circ$ C			2	10	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 25^\circ$ C	$I_F = 3$ A			0.63	V
		$T_j = 25^\circ$ C	$I_F = 6$ A			0.84	
		$T_j = 125^\circ$ C	$I_F = 3$ A		0.5	0.57	
		$T_j = 125^\circ$ C	$I_F = 6$ A		0.67	0.72	

1. Pulse test: $t_p = 380$ μ s, $\delta < 2\%$

To evaluate the conduction losses use the following equation:
 $P = 0.42 \times I_{F(AV)} + 0.050 I_{F(RMS)}^2$

Figure 1. Average forward power dissipation versus average forward current (per diode)

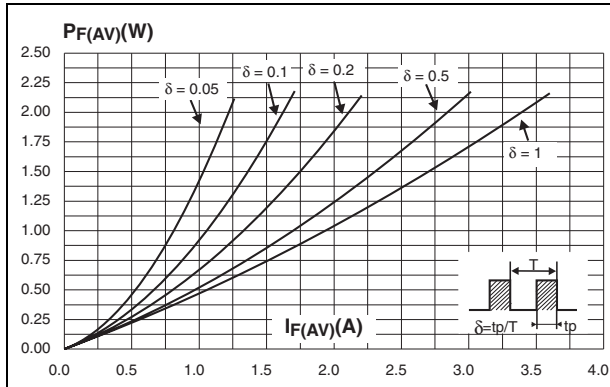


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$, per diode)

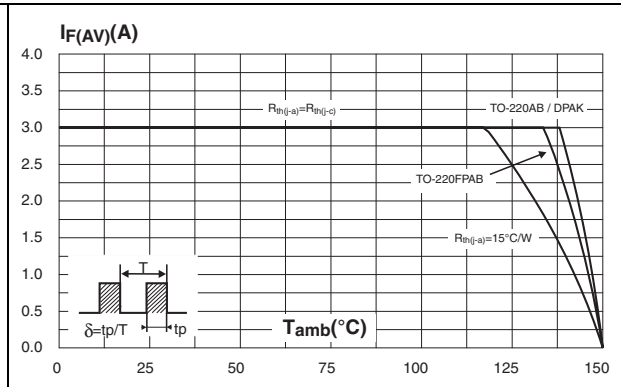


Figure 3. Normalized avalanche power derating versus pulse duration

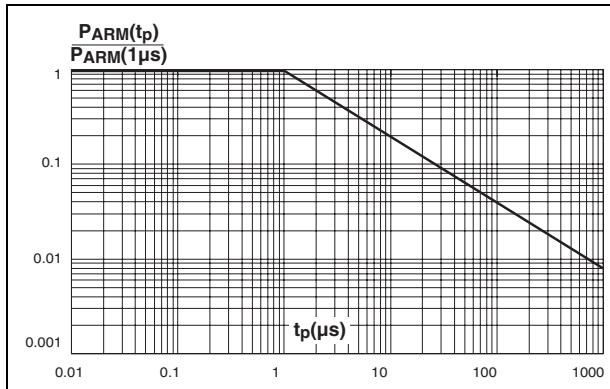


Figure 4. Normalized avalanche power derating versus junction temperature

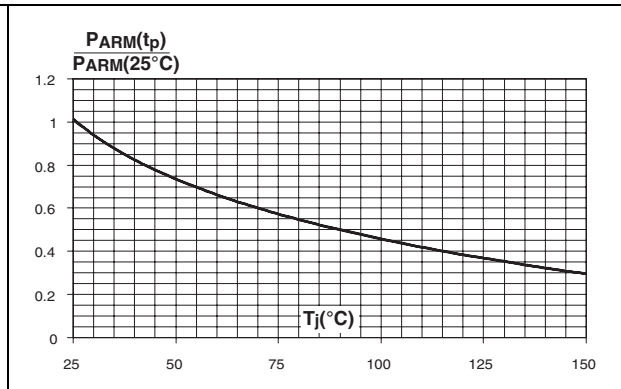


Figure 5. Non repetitive surge peak forward current versus overload duration. (Maximum values, per diode) (TO-220AB / DPAK)

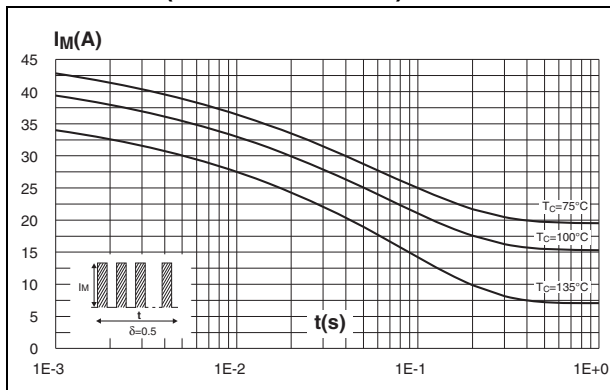


Figure 6. Non repetitive surge peak forward current versus overload duration. (Maximum values, per diode) (TO-220FPAB)

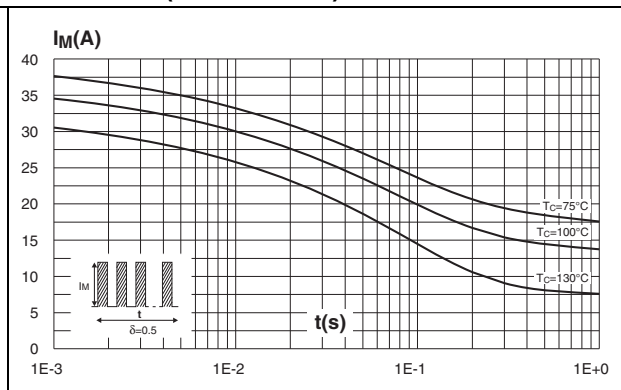


Figure 7. Relative variation of thermal transient impedance junction to case versus pulse duration (TO-220AB/DPAK)

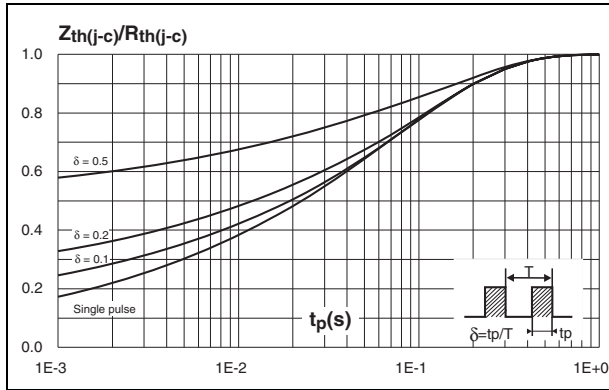


Figure 8. Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAB)

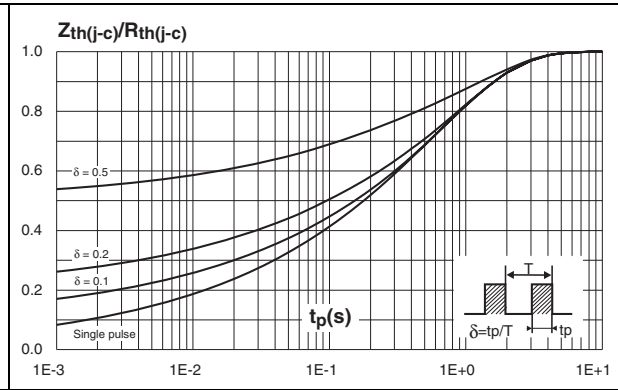


Figure 9. Reverse leakage current versus reverse voltage applied (typical values, per diode)

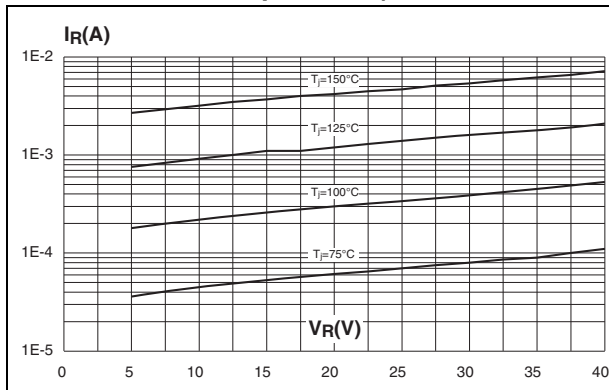


Figure 10. Junction capacitance versus reverse voltage applied (typical values, per diode)

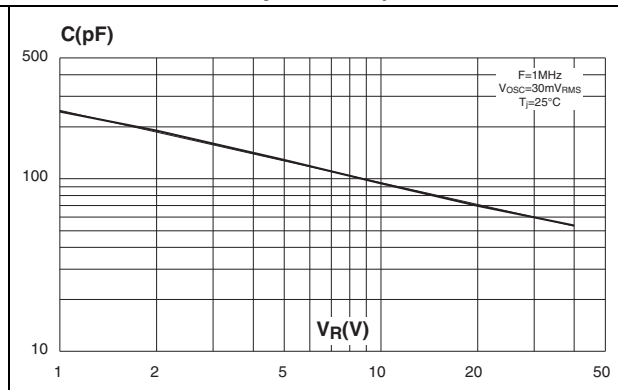


Figure 11. Forward voltage drop versus forward current (maximum values, per diode)

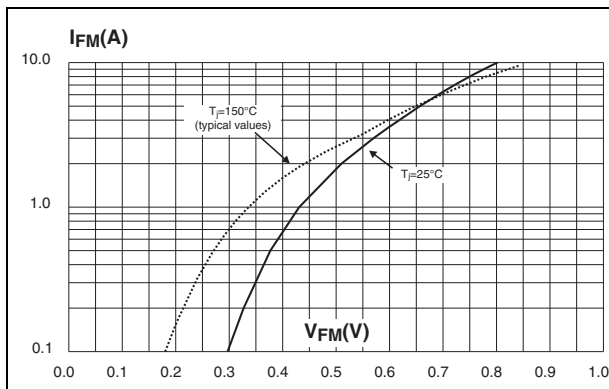
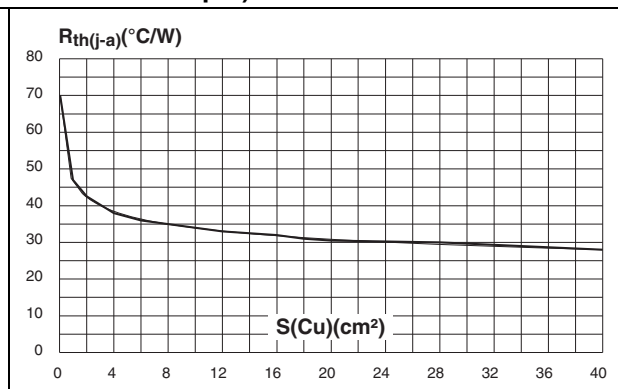


Figure 12. Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35 μm)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 Nm
- Maximum torque value: 0.70 Nm

Table 4. TO-220FPAB dimensions

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

Table 5. DPAK dimensions

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

Figure 13. Footprint (dimensions in millimeters)

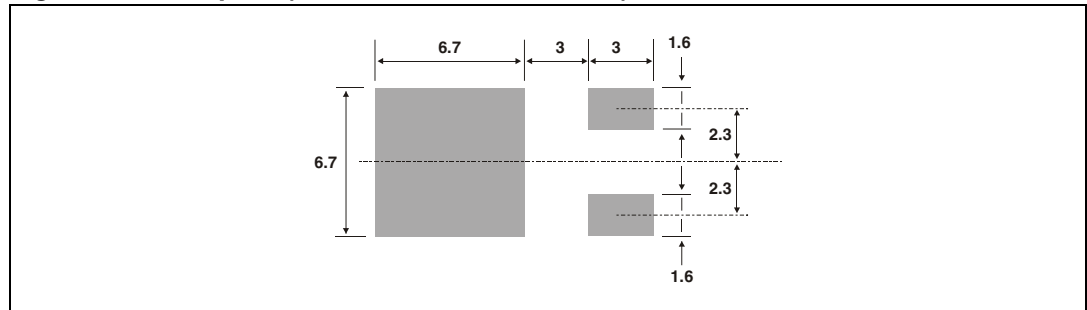


Table 6. TO-220AB dimensions

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

3 Ordering information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS640CT	STPS640CT	TO-220AB	2.20 g	50	Tube
STPS640CB	S640C	DPAK	0.30 g	75	Tube
STPS640CB-TR	S640C	DPAK	0.30 g	2500	Tape and reel
STPS640CFP	STPS640CFP	TO-220FPAB	2.08 g	50	Tube

4 Revision history

Date	Revision	Description of Changes
Aug-2003	6B	Last release.
22-Mar-2007	7	Removed ISOWATT package.

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